

LAMEA System in Package (SiP) Technology Market (2016-2022)

<https://marketpublishers.com/r/LD7CFC9E668EN.html>

Date: January 2017

Pages: 104

Price: US\$ 1,500.00 (Single User License)

ID: LD7CFC9E668EN

Abstracts

The LAMEA System in Package (SiP) Technology Market is would register a growth at a CAGR of 12.4% during the forecast period.

Among applications, consumer electronics segment dominated the LAMEA market in 2015, holding about 28% market share. Growth in portable electronic market, growing popularity of Internet of Things (IoT), and adoption of SiP technology in graphic cards and processors for real world gaming have propelled the market growth.

Telecommunication segment on the other hand is expected to grow at a significant CAGR of around 15.6% during the forecast period, due to growing demand for durable devices with enhanced efficiency.

Integrating circuits and bringing together multiple package assemblies are the key strengths of the SiP technology. The System in Packaging gives faster time to market, lower research and development cost, more integration adaptability and lower research and development cost, more integration adaptability and lower product cost than system on chip (SOC). The System in Packaging has grown into a fastest growing packaging technology segment, facilitating devices such as cellular phones, laptops, cameras and commercial products.

The System-in-Package (SIP) technology has spread into various industrial sectors with a number of packaging types including Flat Packaging, Pin Grid Packaging, Surface Mount and Small Outline Packages. Consumer goods sector, especially the Surface mount technology has witnessed substantial market penetration during the recent years. Surface mount technology (SMT) is a method of mounting electronic components directly on the surface of the printed circuit boards (PCBs) to produce surface mount devices (SMDs).

The report highlights the adoption of System in Package (SiP) Technology in LAMEA (Latin America, Middle East and Africa). Based on the Type, the LAMEA System in Package (SiP) Technology market is segmented into 2-D IC Packaging, 2.5-D IC Packaging and 3-D IC Packaging segments. Based on the Packaging Type, the market is bifurcated into Flat Packages, Pin Grid Arrays, Surface Mount, Small Outline Packages and Other Packaging segments. The LAMEA System in Package (SiP) Technology market is further segmented into Wire Bond, Flip Chip segments based on the Interconnection Technology. Further, the market is segmented into Consumer Electronics, Automotive, Telecommunication, Industrial System, Aerospace & Defense and Other segments based on the various applications. The countries included in the report are Brazil, Argentina, UAE, Saudi Arabia, South Africa, Nigeria and Rest of LAMEA.

Key Players profiled in the report includes Amkor Technology Inc., Jiangsu Changjiang Electronics Technology Co. Ltd., Chipmos Technologies Inc., Powertech Technology Inc., Ase Group, Renesas Electronics Corporation, Samsung Electronics Co. Ltd. and Toshiba Corporation.

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